

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wayne Glenn Renken
Title: System and Method for Heating and Cooling Wafer at Accelerated Rates
Application No.: 10/619,731 Filing Date: July 15, 2003
Examiner: Rakesh K. DHINGRA Group Art Unit: 1763
Docket No.: SENS.007US1 Conf. No.: 7022

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT ACCOMPANYING RCE
AND STATEMENT OF INTERVIEW

Sir:

This is in response to the final Office Action dated December 19, 2005, and is being filed with a Request for Continued Examination. An appropriate request for extension of time accompanies this paper.

Amendments to the Specification are not being made.

Claim Amendments are reflected in the listing of claims, which begins on page 2 of this paper.

Drawing Amendments are not being made.

Remarks begin on page 8 of this paper.